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**IN THE CLAIMS**

1. (Original) A method of packaging a die comprising:
  - electrically connecting the die to a substrate;
  - underfilling the space between the die and the substrate using a capillary underfill; and
  - placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill.
2. (Original) The method of claim 1 wherein the die includes a backside surface and four sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill includes encapsulating the backside surface and the four sidewall surfaces with the pressurized material.
3. (Original) The method of claim 2 wherein the pressurized material is a different material than a material associated with underfilling the space between the substrate and the die.
4. (Original) The method of claim 1 wherein the pressurized material associated with placing a pressurized material in contact with at least a portion of the die is a different material than a material associated with underfilling the space between the substrate and the die.
5. (Original) The method of claim 1 wherein the die includes a backside surface and four sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill excludes placing the pressurized material on the backside surface of the die.
6. (Original) The method of claim 1 wherein the die includes a backside surface and four sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill further includes:
  - placing a film on the backside of the die; and
  - placing the pressurized material on the four sidewall surfaces of the die.

7. (Original) The method of claim 1 wherein the die includes a backside surface and four sidewall surfaces, wherein placing a pressurized material in contact with at least a portion of the die and the substrate after the capillary underfill further includes:

- placing a film on the backside of the die;
- pressurizing the film;
- placing the pressurized material on the four sidewall surfaces of the die; and
- removing the film.

8. (Original) The method of claim 7 wherein the pressurized material is a heated epoxy and wherein the film is removed after the heated epoxy is cured.

9. (Original) The method of claim 7 further comprising transferring heat from the backside surface of the die with a heat transfer device in contact with the backside surface of the die.

10. - 20. (Canceled)

21. (Original) A method of packaging a die comprising:

- attaching the die to a substrate;
- underfilling the space between the die and the substrate with a first material; and
- placing a second material in contact with at least a portion of the die and the substrate after underfilling the space between the die and substrate with the first material.

22. (Original) The method of claim 21 wherein the first material is a curable epoxy.

23. (Original) The method of claim 21 wherein a capillary action of the first material is used in underfilling the space between the die and the substrate.

24. (Original) The method of claim 21 wherein the second material is a curable epoxy.

25. (Original) The method of claim 21 wherein placing a second material in contact with at least a portion of the die and the substrate includes encapsulating the die.

26. (Original) The method of claim 21 wherein placing a second material in contact with at least a portion of the die and the substrate includes partially encapsulating the die.

27. (Original) The method of claim 26 wherein the die includes a backside surface and at least four sidewall surfaces, wherein partially encapsulating the die includes:

placing a film on the backside surface of the die;

applying a force to the film; and

encapsulating the four sidewalls of the die with the second material while leaving the backside surface of the die devoid of the second material.

28. (Original) The method of claim 27 further including removing the film from the backside surface of the die.

29. (Original) The method of claim 21 wherein the die includes a backside surface and at least four sidewall surfaces, wherein placing a second material in contact with at least a portion of the die and the substrate includes leaving the backside surface of the die devoid of the second material.

30. (New) The method of claim 27 further comprising placing a heat sink in thermal communication with the backside surface of the die.

31. (New) The method of claim 27 further comprising:

placing a thermally conductive material on the backside surface of the die; and

placing a heat sink onto the conductive material.

32. (New) The method of claim 21 further comprising etching the device.

33. (New) The method of claim 21 wherein placing a second material in contact with at least a portion of the die and the substrate further includes pressurizing the second material.

34. (New) The method of claim 1 further comprising etching the device.

35. (New) The method of claim 1 further comprising:  
allowing the underfill material to at least partially cure; and  
etching the device.

36. (New) The method of claim 5 further comprising placing a thermally conductive material onto the backside surface of the die.

37. (New) The method of claim 5 further comprising:  
placing a thermally conductive material onto the backside surface of the die; and  
placing a heat sink onto the thermally conductive material.

38. (New) The method of claim 5 further comprising placing a heat sink in thermal communication with the backside surface of the die.

39. (New) The method of claim 1 further comprising placing a heat sink in thermal communication with the die.

40. (New) The method of claim 5 further comprising placing another encapsulating material onto the backside surface of the die.